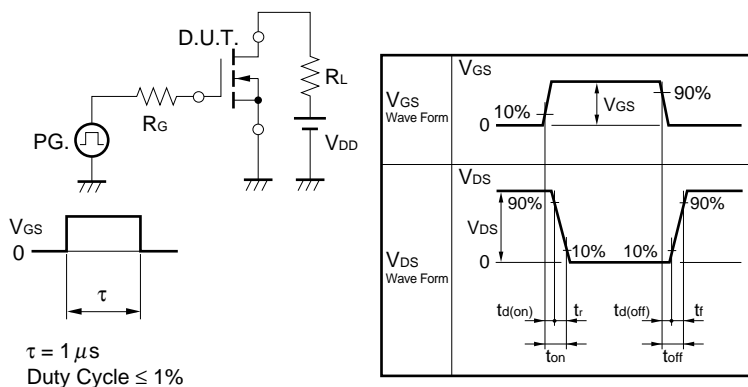


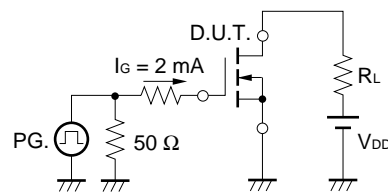
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V			10	μA
Gate Leakage Current	I _{GSS}	V _{GS} = ±12 V, V _{DS} = 0 V			±10	μA
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1.0 mA	0.5	1.0	1.5	V
Forward Transfer Admittance	y _{fs}	V _{DS} = 10 V, I _D = 3.0 A	5.0			S
Drain to Source On-state Resistance	R _{DS(on)1}	V _{GS} = 4.5 V, I _D = 3.0 A	13.0	18.0	23.0	mΩ
	R _{DS(on)2}	V _{GS} = 4.0 V, I _D = 3.0 A	14.0	19.0	24.0	mΩ
	R _{DS(on)3}	V _{GS} = 3.1 V, I _D = 3.0 A	14.5	21.5	28.0	mΩ
	R _{DS(on)4}	V _{GS} = 2.5 V, I _D = 3.0 A	15.0	24.5	29.0	mΩ
Input Capacitance	C _{iss}	V _{DS} = 10 V		705		pF
Output Capacitance	C _{oss}	V _{GS} = 0 V		205		pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0 MHz		145		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 10 V, I _D = 3.0 A		60		ns
Rise Time	t _r	V _{GS} = 4.0 V		310		ns
Turn-off Delay Time	t _{d(off)}	R _G = 10 Ω		380		ns
Fall Time	t _f			420		ns
Total Gate Charge	Q _G	V _{DD} = 16 V		9.0		nC
Gate to Source Charge	Q _{GS}	V _{GS} = 4.0 V		2.0		nC
Gate to Drain Charge	Q _{GD}	I _D = 6.0 A		4.0		nC
Body Diode Forward Voltage	V _{F(S-D)}	I _F = 6.0 A, V _{GS} = 0 V		0.84		V
Reverse Recovery Time	t _{rr}	I _F = 6.0 A, V _{GS} = 0 V		480		ns
Reverse Recovery Charge	Q _{rr}	di/dt = 50 A / μs		1200		nC

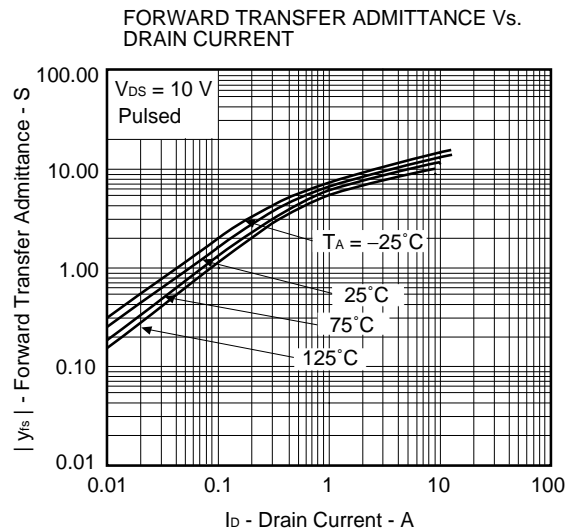
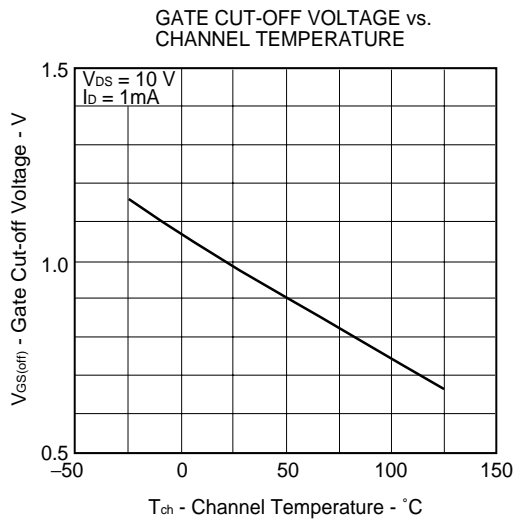
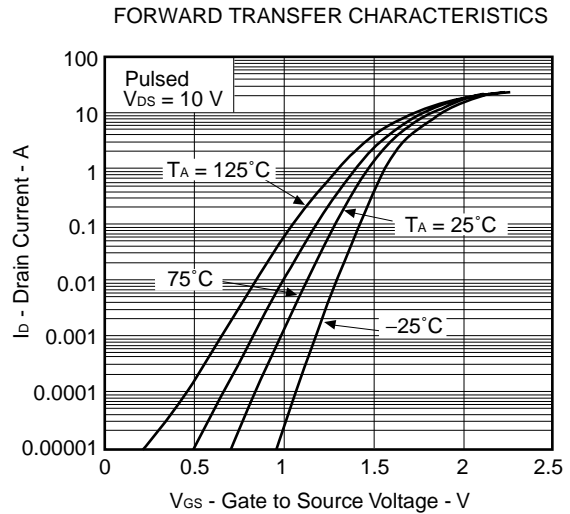
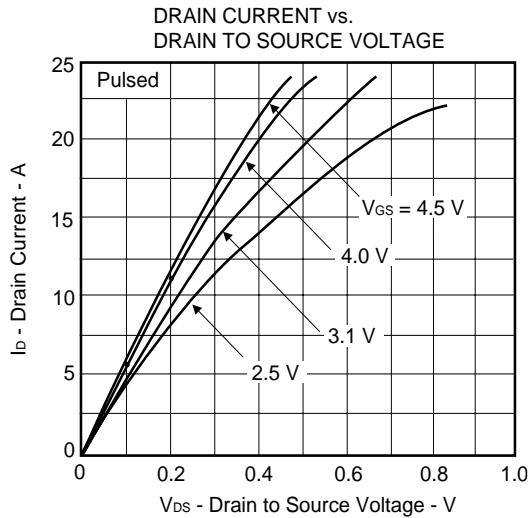
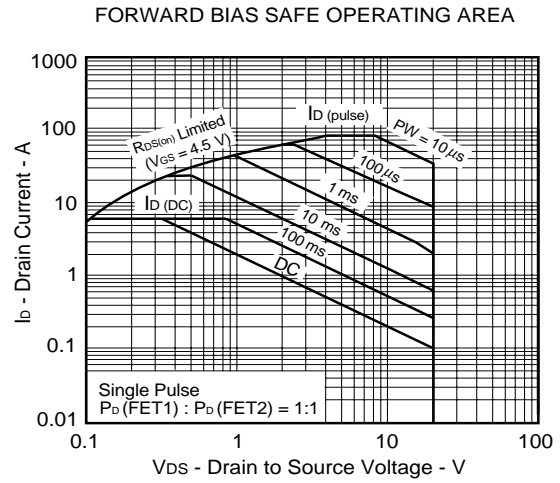
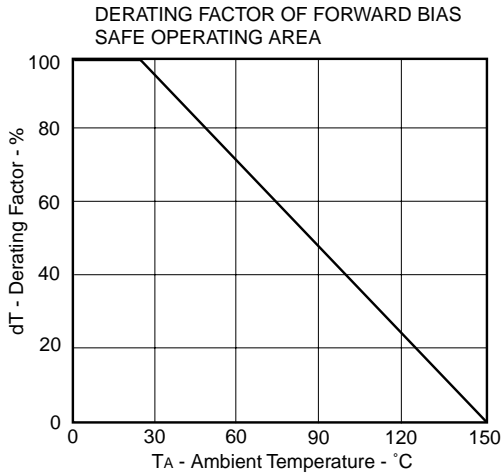
TEST CIRCUIT 1 SWITCHING TIME

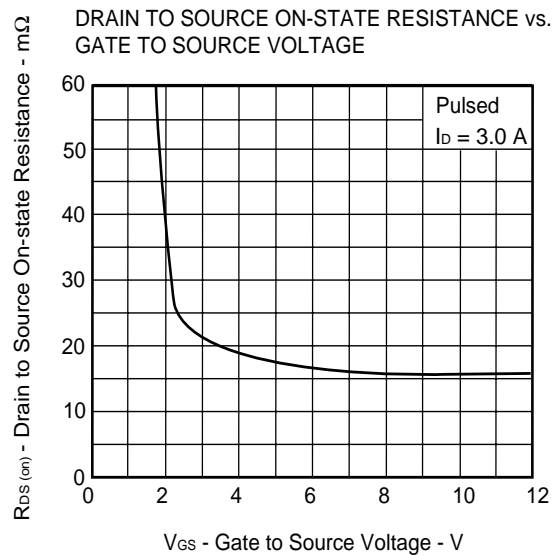
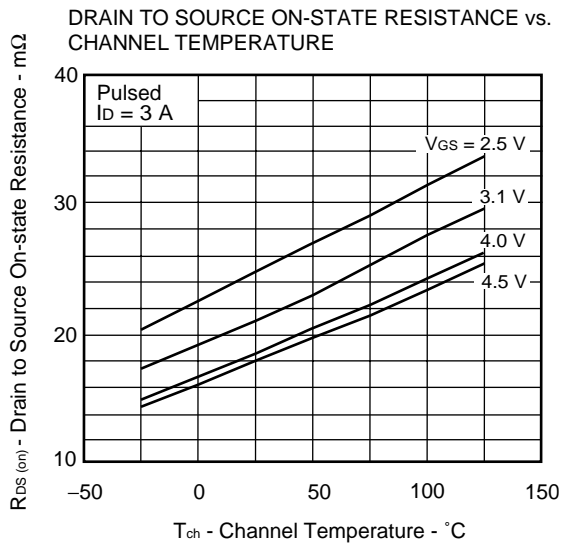
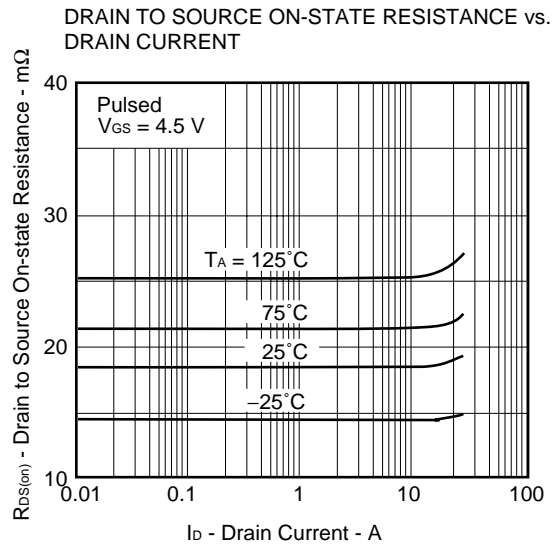
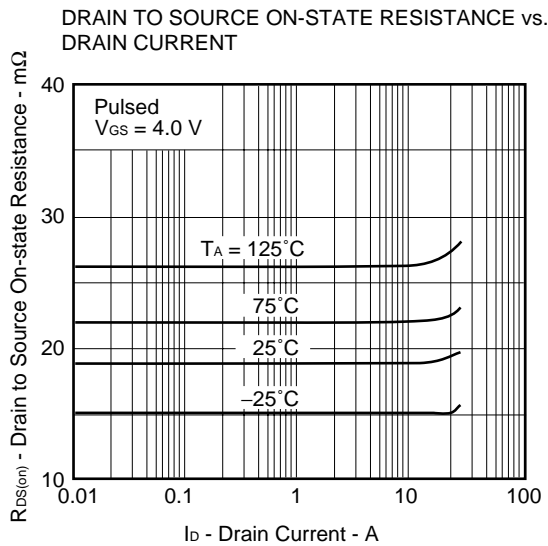
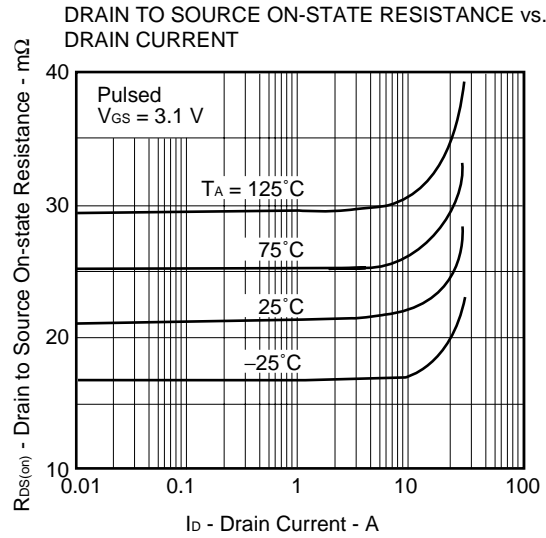
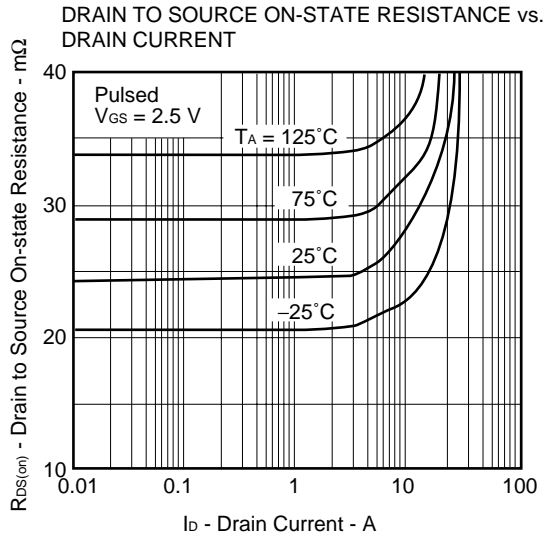


TEST CIRCUIT 2 GATE CHARGE

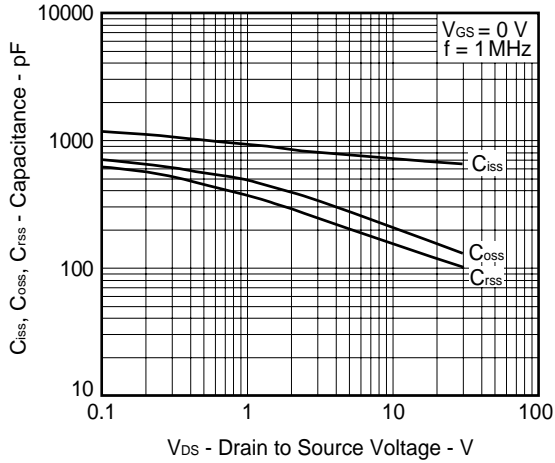


TYPICAL CHARACTERISTICS (T_A = 25°C)

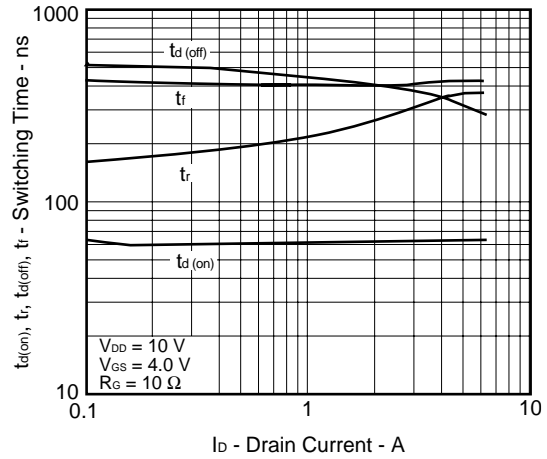




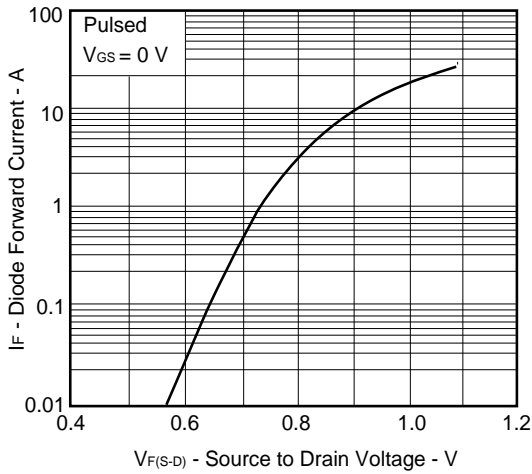
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



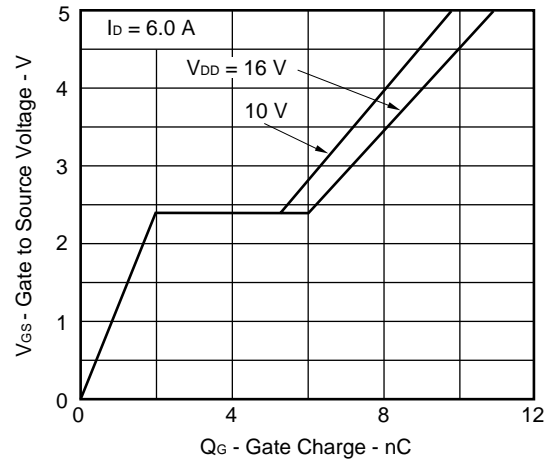
SWITCHING CHARACTERISTICS



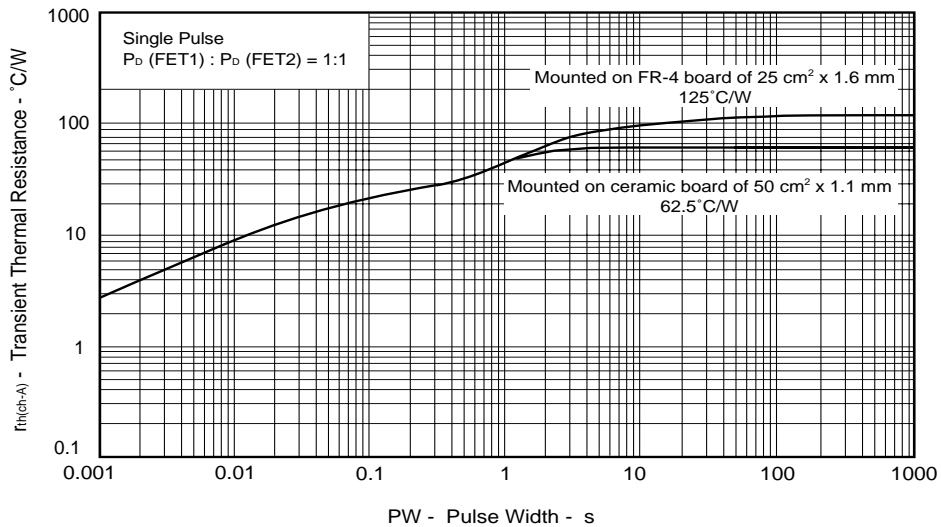
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



[MEMO]

[MEMO]

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